3. (Amended) The method of claim 1 wherein the non-black, optically transmissive material is adapted to provide protection from damage as the result of environmental and handling factors.

6. (Amended) The method of claim 1 wherein the non-black, optically transmissive material prevents remarking indicia or identification marks on the chip.

9. (Amended) A method of marking an electronic integrated circuit chip having surfaces comprising the following steps:

forming a semiconductor, integrated circuit chip having surfaces including a planar front surface, a planar back surface and edges of the chip between the planar surfaces with at least one electrical contact site on a surface,

forming internal marking indicia upon an exterior marking portion of a surface of the chip for identification of the chip, and

forming a non-black layer covering the exterior surface of the chip at least at the exterior marking portion thereof, the non-black layer being composed, of a colored, optically transmissive material, which non-black layer cannot be scraped off of the chip for preventing replacement of the internal marking indicia by different markings and for preventing remarking the internal indicia on the exterior marking surface of the chip,

whereby the indicia are visible through the non-black layer.

Cancel claim 11.

12. (Amended) A method of marking a chip having surfaces comprising:

forming internal marking indicia on a marking location upon an exterior surface of the chip, and

forming a non-black, optically transparent material colored with a particular color over at least the marking location on that exterior surface of the chip wherein the material colored with the particular color together with the marking indicia represents identification of the chip which non-black, optically transparent, colored material cannot be scraped off of the chip for prevention of replacement of the internal marking indicia by different markings.

13. (Amended) A chip comprising:

the chip having exterior surfaces,

internal marking indicia formed on a marking location upon an exterior surface of the chip for identification of the chip, and

a non-black, optically transmissive material formed over at least the marking location on the one exterior surface of the chip which non-black, optically transmissive material cannot be scraped off for prevention of replacement of the internal marking indicia by different markings.

14. (Amended) The chip of claim 13 wherein the non-black, optically transmissive material comprises a non-black, transparent or semi-transparent material.

15. (Amended) The chip of claim 13 wherein the non-black, optically transmissive material comprises a colored material.

16. (Amended) The chip of claim 13 wherein the non-black, optically transmissive material prevents remarking indicia or identification marks on the chip.

17. (Amended) The chip of claim 13 wherein the non-black, optically transmissive material prevents remarking silicon for a semiconductor package and the optically transmissive material is a transparent material.

18. (Amended) The chip of claim 13 wherein:

illumination means are provided for directing electromagnetic radiation upon the internal marking indicia through the non-black optically transmissive material and

reading means are provided for reading the internal marking indicia in response to images of the internal marking indicia provided by reflections of the electromagnetic radiation.

19. (Amended) The chip of claim 13 wherein the non-black, optically transmissive material is adapted to provide protection from damage as the result of environmental and handling factors.

20. (Amended) The chip of claim 14 wherein:

illumination means are provided for directing electromagnetic radiation upon the internal marking indicia through the non-black optically transmissive material and

reading means are provided for reading the internal marking indicia in response to images of the internal marking indicia provided by reflections of the electromagnetic radiation.

21. (Amended) The chip of claim 17 wherein:

illumination means are provided for directing electromagnetic radiation upon the internal marking indicia through the non-black optically transmissive material and

reading means are provided for reading the internal marking indicia in response to images of the internal marking indicia provided by reflections of the electromagnetic radiation.

22. (Amended) An electronic integrated circuit chip comprising:

a semiconductor, integrated circuit chip having surfaces including a planar front surface, a planar back surface and edges of the chip between the planar surfaces with at least one electrical contact site on a surface,

indicia marked upon an exterior marking portion of a surface of the chip for identification of the chip,

a non-black layer covering the exterior surface of the chip at least at the exterior marking portion thereof, the non-black layer being composed,

of a colored, optically transmissive material which non-black, optically transmissive material cannot be scraped off of the chip for prevention of replacement of the indicia by different markings and for preventing remarking the indicia on the exterior marking surface of the chip, and

the indicia being visible through the non-black layer.

Amend

23. (Amended) The chip of claim 22 wherein:

illumination means are provided for directing electromagnetic radiation upon the internal marking indicia through the non-black optically transmissive material and

reading means are provided for reading the internal marking indicia in response to images of the internal marking indicia provided by reflections of the electromagnetic radiation.

Cancel claim 24.

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25. (Amended) A chip comprising:

internal marking indicia formed on a marking location upon an exterior surface of the chip, and

a non-black, optically transparent material colored with a particular color formed over at least the marking location on that exterior surface of the chip wherein the material colored with the particular color together with the marking indicia represents identification of the chip which non-black, optically transmissive material cannot be scraped off of the chip for prevention of replacement of the internal marking indicia by different markings.

REMARKS

The claims have been amended in view of the Office action and in view of the remarks which follow, they are believed to be in condition for allowance.

Claim Objections

In paragraph 2 of the Office Action objections were made as to claims 3,6, 11, 12, 16, 19, 24, and 25 because of the informalities as follows:

"Re claim 3 and 18 line 2: Replace "the silicon" with -- silicon --."
"Re claims 6 and 16 line 2: Replace "the device" with -- the chip --."
"Re claims 11 and 24 line 3: Replace "the particular" with -- the particular material layer color --, and replace "the identification" with-- identification --."
"Re claims 12 and 25 line 6: Replace "the particular" with -- the material --.
"Appropriate correction is required."

Corrections have been made which while at variance with some of the suggestions (which were nevertheless appreciated and helpful in revising the claims) are believed to